

NLX2GU04

Dual Unbuffered Inverter

The NLX2GU04 MiniGate™ is an advanced high-speed CMOS dual unbuffered inverter in ultra-small footprint.

This device is well suited for use in oscillator, pulse-shaping and high input impedance amplifier applications. For digital applications, the NLX2G04 is recommended.

The NLX2GU04 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

Features

- Designed for 1.65 V to 5.5 V V_{CC} Operation
- Unbuffered for Crystal Oscillator and Analog Applications
- 16 mA Balanced Output Source and Sink Capability
- Balanced Propagation Delays
- Ovvoltage Tolerant (OVT) Input and Output Pins
- Ultra-Small Packages
- These are Pb-Free Devices

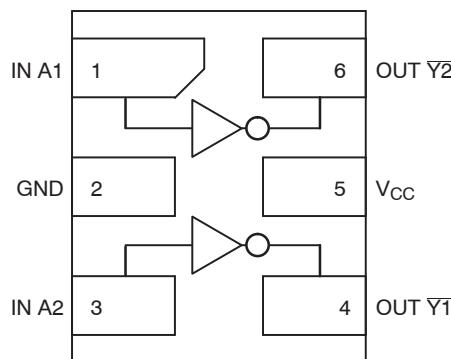


Figure 1. Pinout (Top View)

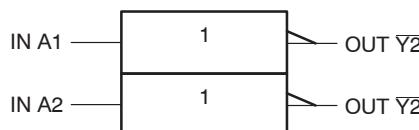


Figure 2. Logic Symbol

PIN ASSIGNMENT

1	IN A1
2	GND
3	IN A2
4	OUT Y2
5	V _{CC}
6	OUT Y1

FUNCTION TABLE

A	Y
L	H
H	L



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MARKING DIAGRAMS

	ULLGA6 1.0 x 1.0 CASE 613AD	
	ULLGA6 1.2 x 1.0 CASE 613AE	
	ULLGA6 1.45 x 1.0 CASE 613AF	
	UDFN6 1.0 x 1.0 CASE 517BX	
	UDFN6 1.2 x 1.0 CASE 517AA	
	UDFN6 1.45 x 1.0 CASE 517AQ	

L = Device Marking
M = Date Code

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage	-0.5 to +7.0	V
V_{IN}	DC Input Voltage	-0.5 to +7.0	V
V_{OUT}	DC Output Voltage	-0.5 to +7.0	V
I_{IK}	DC Input Diode Current $V_{IN} < GND$	-50	mA
I_{OK}	DC Output Diode Current $V_{OUT} < GND$	-50	mA
I_O	DC Output Source/Sink Current	± 50	mA
I_{CC}	DC Supply Current Per Supply Pin	± 100	mA
I_{GND}	DC Ground Current per Ground Pin	± 100	mA
T_{STG}	Storage Temperature Range	-65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
T_J	Junction Temperature Under Bias	150	°C
MSL	Moisture Sensitivity	Level 1	
F_R	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
$I_{LATCHUP}$	Latchup Performance Above V_{CC} and Below GND at 125 °C (Note 5)	± 500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
2. Tested to EIA/JESD22-A114-A.
3. Tested to EIA/UESD22-A115-A.
4. Tested to JESD22-C101-A.
5. Tested to EIA / JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CC}	Positive DC Supply Voltage	1.65	5.5	V
V_{IN}	Digital Input Voltage	0	5.5	V
V_{OUT}	Output Voltage	0	5.5	V
T_A	Operating Free-Air Temperature	-55	+125	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0 0	100 20	ns/V

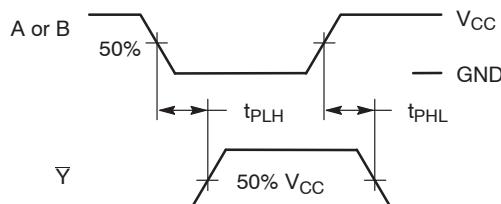
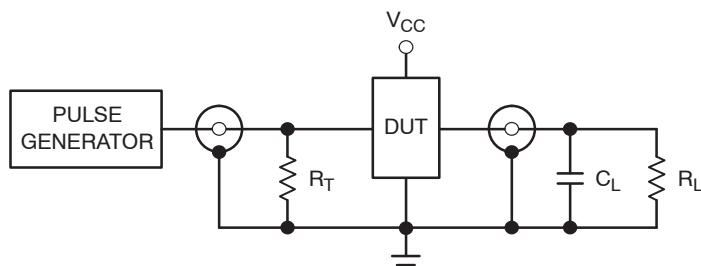
DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = 25 °C			T _A = +85°C		T _A = -55°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
V _{IH}	Low-Level Input Voltage		1.65 2.3 to 5.5	0.85 x V _{CC} 0.80 x V _{CC}			0.85 x V _{CC} 0.80 x V _{CC}		0.85 x V _{CC} 0.80 x V _{CC}		V
V _{IL}	Low-Level Input Voltage		1.65 2.3 to 5.5			0.15 x V _{CC} 0.20 x V _{CC}		0.15 x V _{CC} 0.20 x V _{CC}		0.15 x V _{CC} 0.20 x V _{CC}	V
V _{OH}	High-Level Output Voltage	V _{IN} = V _{IH} or V _{IL} I _{OH} = -100 µA	1.65 to 5.5	V _{CC} - 0.1	V _{CC}		V _{CC} - 0.1		V _{CC} - 0.1		V
		V _{IN} = V _{IH} or V _{IL} I _{OH} = -3 mA I _{OH} = -4 mA I _{OH} = -6 mA I _{OH} = -8 mA I _{OH} = -12 mA I _{OH} = -16 mA	1.65 2.3 2.7 3.0 3.0 4.5	1.29 1.9 2.2 2.4 2.3 3.8	1.52 2.1 2.3 2.6 2.5 4.0		1.29 1.9 2.2 2.4 2.3 3.8		1.29 1.9 2.2 2.4 2.3 3.8		
V _{OL}	Low-Level Output Voltage	V _{IN} = V _{IH} or V _{IL} I _{OL} = 50 µA	1.65 to 5.5			0.1		0.1		0.1	V
		V _{IN} = V _{IH} or V _{IL} I _{OH} = 3 mA I _{OH} = 4 mA I _{OH} = 6 mA I _{OH} = 8 mA I _{OH} = 12 mA I _{OH} = 16 mA	1.65 2.3 2.7 3.0 3.0 4.5		0.08 0.12 0.2 0.24 0.36 0.31	0.24 0.3 0.4 0.4 0.55 0.55		0.24 0.3 0.4 0.4 0.55 0.55		0.24 0.3 0.4 0.4 0.55 0.55	
I _{IN}	Input Leakage Current	0 ≤ V _{IN} ≤ 5.5 V	0 to 5.5			±0.1		±1.0		±1.0	µA
I _{OFF}	Power-Off Output Leakage Current	V _{OUT} = 5.5 V	0			1.0		10		10	µA
I _{CC}	Quiescent Supply Current	0 ≤ V _{IN} ≤ V _{CC}	5.5			1.0		10		10	µA

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0$ ns)

Symbol	Parameter	V _{CC} (V)	Test Condition	T _A = 25 °C			T _A = -55°C to +125°C		Unit
				Min	Typ	Max	Min	Max	
t _{PLH} , t _{PHL}	Propagation Delay, Input A to Output Y	1.65 to 1.95	R _L = 1 MΩ, C _L = 15 pF	1.5	1.8	5.5	1.5	11	ns
			R _L = 1 MΩ, C _L = 15 pF	1.2	3.3	5.7	1.2	6.3	
		3.0 to 3.6	R _L = 1 MΩ, C _L = 15 pF	0.8	2.7	4.1	0.8	4.5	
			R _L = 500 Ω, C _L = 50 pF	1.2	4.0	6.4	1.2	7.0	
		4.5 to 5.5	R _L = 1 MΩ, C _L = 15 pF	0.5	2.2	3.3	0.5	3.6	
			R _L = 500 Ω, C _L = 50 pF	0.8	3.4	5.6	0.8	6.2	
C _{IN}	Input Capacitance	5.5	V _{IN} = 0 V or V _{CC}		7				pF
C _{OUT}	Output Capacitance	5.5	V _{IN} = 0 V or V _{CC}		8				pF
C _{PD}	Power Dissipation Capacitance (Note 6)	5.5	10 MHz V _{IN} = 0 V or V _{CC}		25				pF

6. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no-load dynamic power consumption: P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.


Figure 3. Switching Waveforms


R_T = Z_{OUT} of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

NLX2GU04

ORDERING INFORMATION

Device	Package	Shipping [†]
NLX2GU04AMX1TCG	ULLGA6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLX2GU04BMX1TCG	ULLGA6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLX2GU04CMX1TCG	ULLGA6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel
NLX2GU04MUTCG	UDFN6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLX2GU04AMUTCG	UDFN6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLX2GU04AMUTCG	UDFN6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel

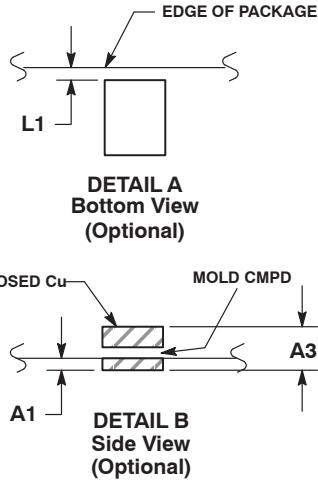
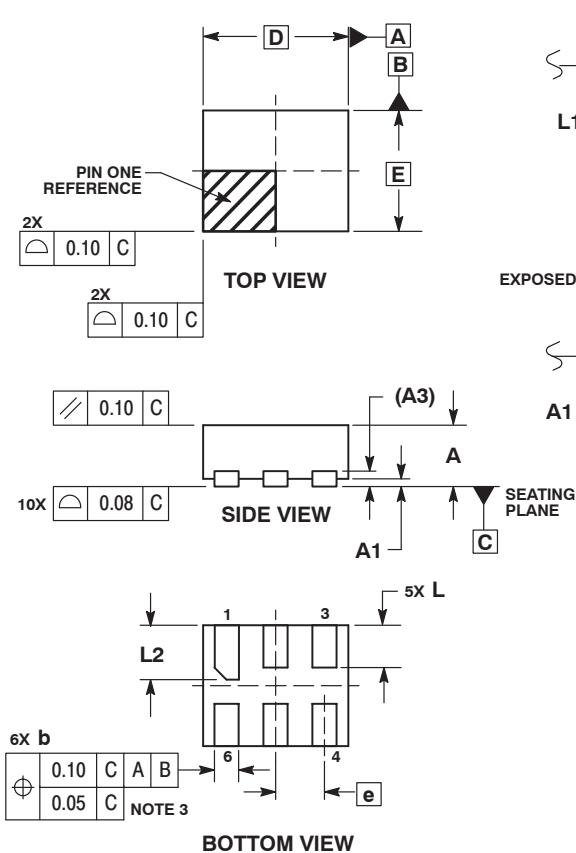
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

UDFN6 1.2x1.0, 0.4P

CASE 517AA

ISSUE O

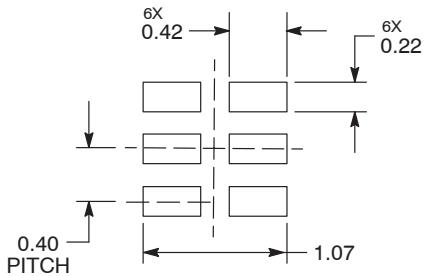


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.127 REF	
b	0.15	0.25
D	1.20 BSC	
E	1.00 BSC	
e	0.40 BSC	
L	0.30	0.40
L1	0.00	0.15
L2	0.40	0.50

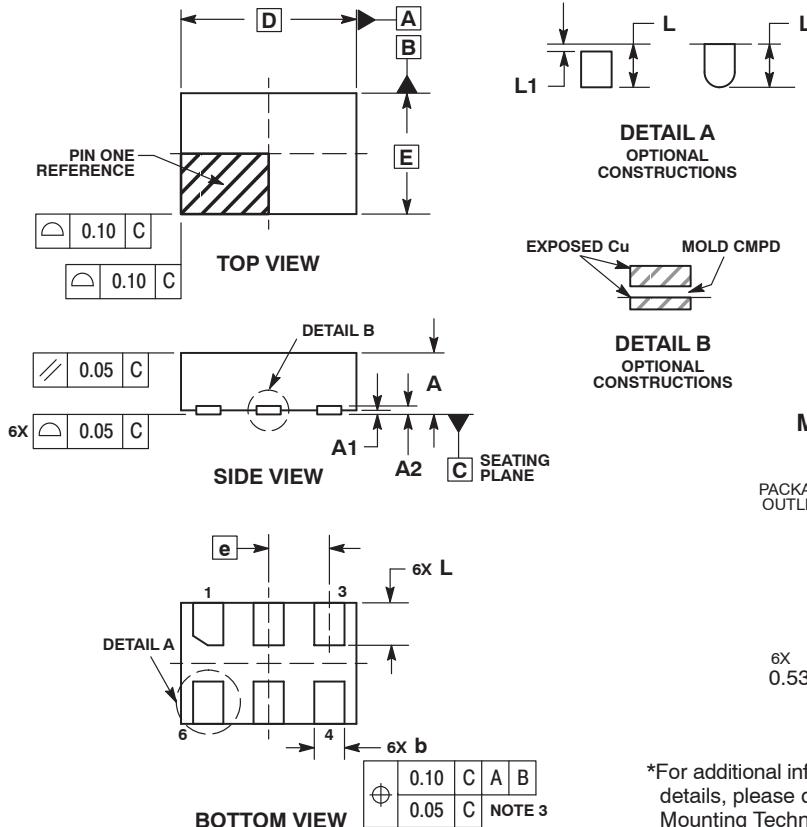
MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

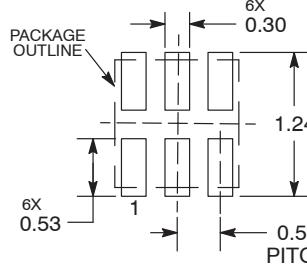
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

UDFN6 1.45x1.0, 0.5P
CASE 517AQ
ISSUE O

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A2	0.07	REF
b	0.20	0.30
D	1.45	BSC
E	1.00	BSC
e	0.50	BSC
L	0.30	0.40
L1	---	0.15

MOUNTING FOOTPRINT



DIMENSIONS: MILLIMETERS

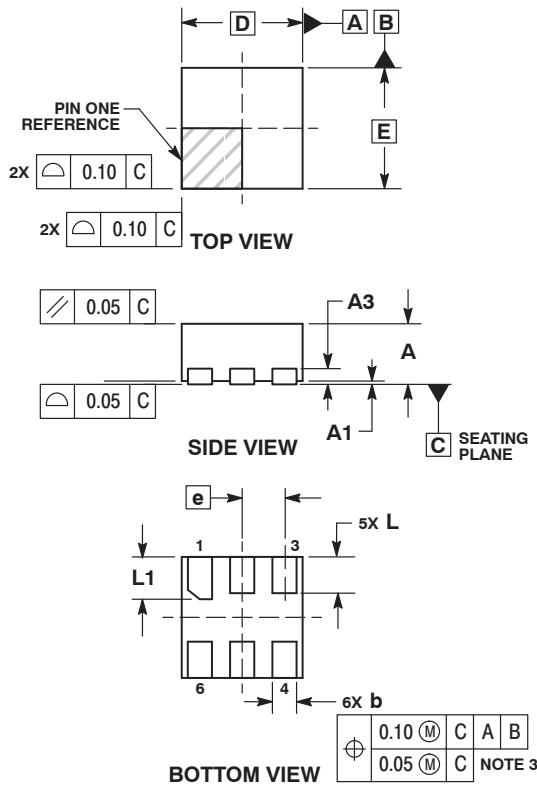
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PACKAGE DIMENSIONS

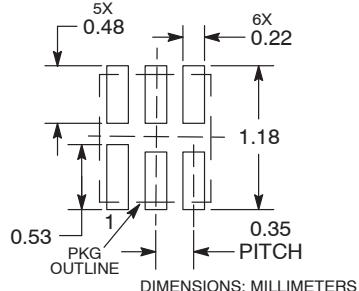
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CASE 517BX

ISSUE O



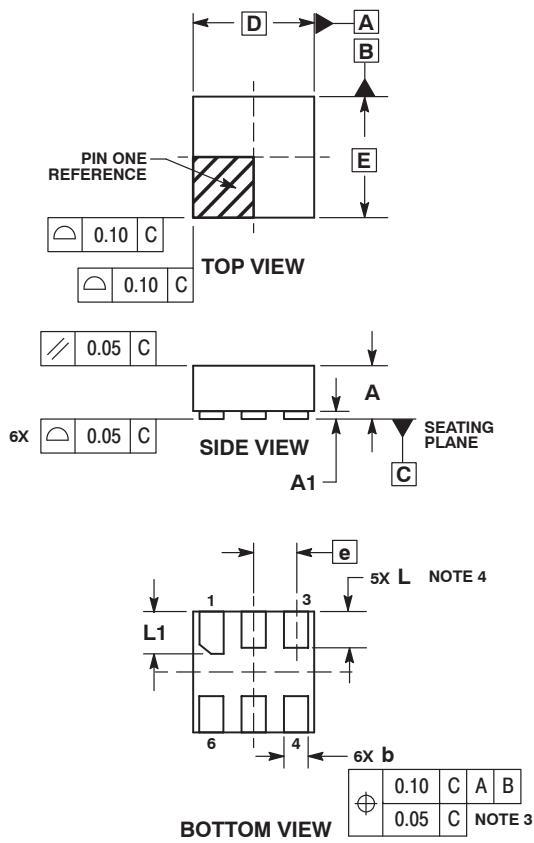
DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13	REF
<i>b</i>	0.12	0.22
D	1.00	BSC
E	1.00	BSC
e	0.35	BSC
L	0.25	0.35
L1	0.30	0.40

RECOMMENDED
SOLDERING FOOTPRINT*

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

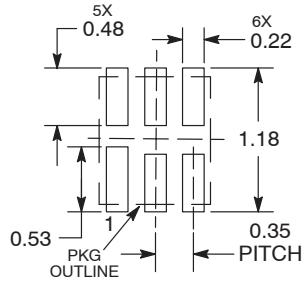
ULLGA6 1.0x1.0, 0.35P

CASE 613AD
ISSUE A

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION *b* APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.40
A1	0.00	0.05
b	0.12	0.22
D	1.00 BSC	
E	1.00 BSC	
e	0.35 BSC	
L	0.25	0.35
L1	0.30	0.40

MOUNTING FOOTPRINT
SOLDERMASK DEFINED*

DIMENSIONS: MILLIMETERS

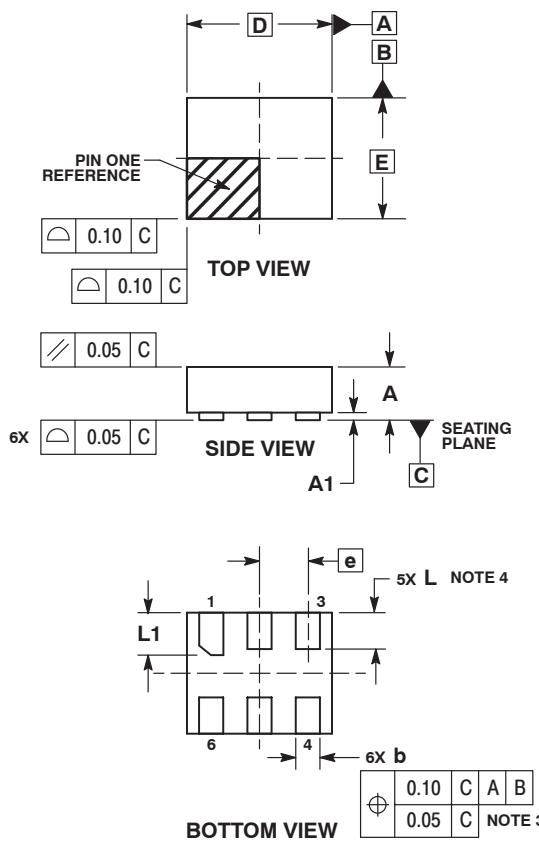
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

ULLGA6 1.2x1.0, 0.4P

CASE 613AE

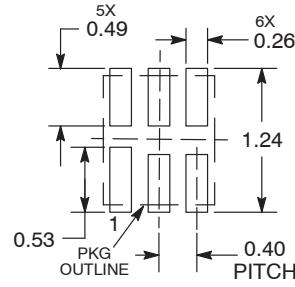
ISSUE A



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION *b* APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.40
A1	0.00	0.05
b	0.15	0.25
D	1.20 BSC	
E	1.00 BSC	
e	0.40 BSC	
L	0.25	0.35
L1	0.35	0.45

MOUNTING FOOTPRINT
SOLDERMASK DEFINED*

DIMENSIONS: MILLIMETERS

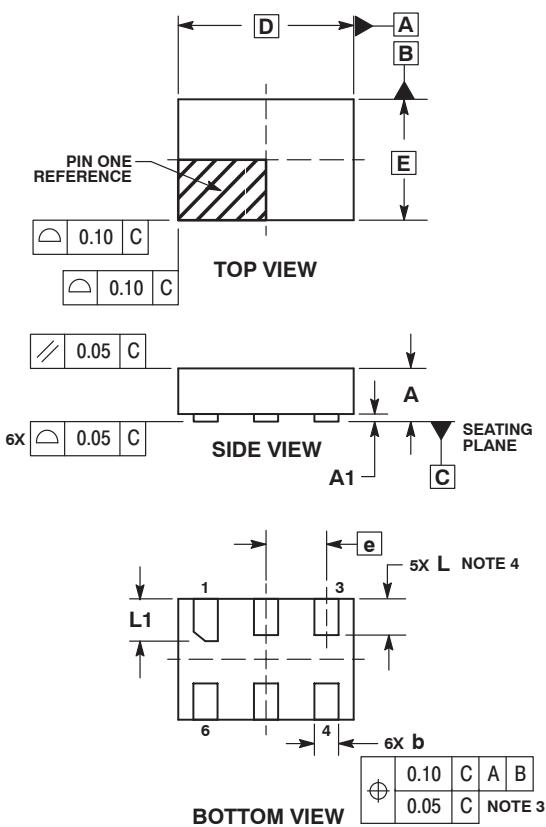
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PACKAGE DIMENSIONS

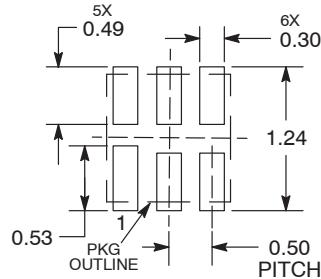
ULLGA6 1.45x1.0, 0.5P

CASE 613AF

ISSUE A



DIM	MILLIMETERS		
	MIN	MAX	
A	---	0.40	
A1	0.00	0.05	
b	0.15	0.25	
D	1.45 BSC		
E	1.00 BSC		
e	0.50 BSC		
L	0.25	0.35	
L1	0.30	0.40	

MOUNTING FOOTPRINT
SOLDERMASK DEFINED*

DIMENSIONS: MILLIMETERS

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